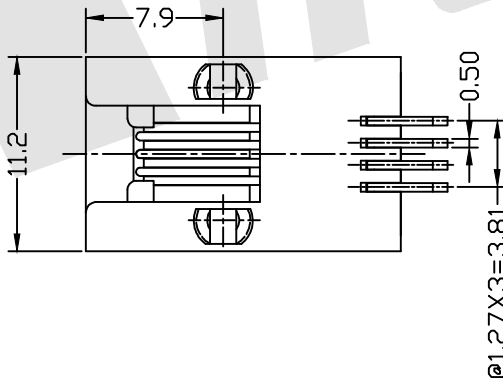
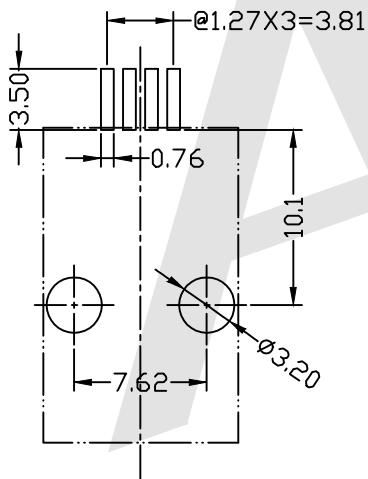
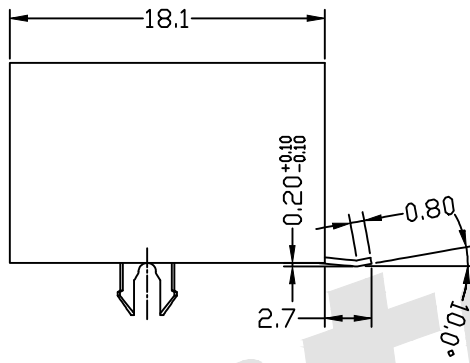
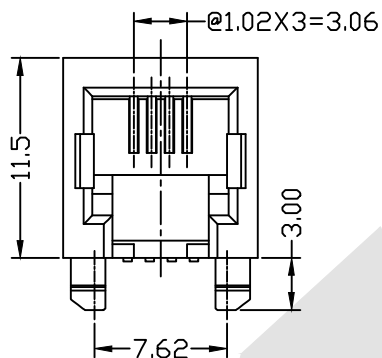


HSF



PC BOARD LAYOUT  
COMPONENT SIDE SHOWN

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm
3. PLATING: SELECTING GOLD PLATING 1u"~50u" OVER NICKEL IN CONTACT AREA. 150u" TIN PLATING OVER NICKEL IN SOLDER AREA.

4. SHIELD: 0.25mm THICKNESS COPPER ALLY WITH NICKEL . PLATEL

ELECTRICAL:

1. VOLTAGE PATING : 125 VAC RMS.
2. CURRENT PATING : 1.5 AMP
3. CONTACT RESISTANCE: 35 MILLIOHMS MAX
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500V DC.
5. DIELECTRIC WITHSTANDING RESISTANCE: 1000V AC RMS 60Hz. 1MIN

MECHANICAL:

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRE-SOLDER : 10LB MIN

ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C .
2. OPERATION: -40°C TO +85°C .
3. IR REFLOW SOLDERING

TEMPERRATURE: 255~265°C (5~10 SECONDS) MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68 SUBPART F.

Order Code:

ATRJ5822 - 4P - 4C - X - A - X

①      ②      ③      ④      ⑤      ⑥

① SERIES NO:

② NUMBER OF POSITIONS(8P, 6P, 4P)

③ NUMBER OF CONTACTS(8C, 6C, 4C)

④ Contact Plating

G0: Gold flash

G1: 3U" Gold

G2: 5U" Gold

G3: 10U" Gold

G4: 15U" Gold

G5: 30U" Gold

SN: Tin

⑤ Shield

A: W/O Shield

B: Half Shield

C: Shield W/Eml

D: Shield W/O Eml

⑥ packing:

A: Tray packing

R: Tape & Reel

Unless Otherwise specified tolerance

X. ±0.35 X.XX: ±0.20

X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown

UNIT: mm

DRAW Wu Feng Rong

DATE 22/03/2018

CHECK BobYang

DATE 22/03/2018



ANTENK ELECTRONICS CO., LTD

Http://www.antenk.com

E-mail:sales@antenk.com

TITLE:

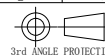
SIDE ENTRY SMT JACK 4P

DRAWING NO:

ATRJ5822-4P4C-X-A-X

PRODUCT NO:

ATRJ5822-4P4C-X-A-X



3rd ANGLE PROJECTION

| REV | DESCRIPTION | DATE |
|-----|-------------|------|
| 1   |             |      |
| 2   |             |      |
| 3   |             |      |
| 4   |             |      |
| 5   |             |      |